



PATENT

Atty. Dkt. No. APPM/005619/DSM/LOW KJW

2893
JW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Nguyen, et al.

Serial No.: 09/912,103

Confirmation No.: 4476

Filed: July 23, 2001

For: Selective Etching of
Organosilicate Films Over
Silicon Oxide Stop Etch LayersMAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

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§ Group Art Unit: 2823
§
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§§ Examiner: Khiem D. Nguyen
§
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§
§CERTIFICATE OF MAILING
37 CFR 1.8

I hereby certify that this correspondence is being deposited on November 30, 2005 with the United States Postal Service as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

November 30, 2005
Date

Keith M. Tackett

RESPONSE TO OFFICE ACTION DATED AUGUST 5, 2005

In response to the Office Action dated August 5, 2005, having a shortened statutory period for response with a one month extension set to expire on December 5, 2005, copy attached hereto, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicants believe that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPN/005619/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

The Pending Claims are reflected in the listing of claims which begins on page 2 of this paper. Remarks begin on page 6 of this paper.